

Minilab	
Technical Data - Overview	
Carrier Size (mm)	
Length	304
Depth	274
Height on Batch Carrier	80 *2
Maximum Board Size (mm) - Double sided boards	
Depth	254
Edge clearance	Variable (3 - 6,5)
Maximum Board weight (kg)	
Per carrier	2
Times	
Heat Up Time (min)	15
Cycle Time per carrier (sec)	> 240 (depending on the Solder Profile)
Liquid - Galden	
Liquid Agent Filling (kg)	3
Consumption (g/h)	~ 10
Electrics	
Voltage	208-240 VAC - 50/60Hz (1 Phase, Neutral und PE)
Connecting Power (kW)	1,5
Main Fuse (A) (Type "gl" or C")	16
SCCR, Icc (kA)	1,0
Heating Capacity Vapour Phase (kW)	1,8
Ø Vapour Phase (kWh)	0,8
Ø in Standby (kWh)	0,5
Water	
Optional Cooling Device	1-TH
Flow (l/min)	1,0
Water Temperature (°C)	17 - 23
Hose (Inch)	½
Pressure (bar / PSI)	2,5 - 5 / 37 - 58
Ph- Value	6,5 – 8,5
Hardness GH (°dH/l)	< 12
Electric Conductivity LF (µS/cm)	2 < LF < 100

* Technical changes reserved *

*2 A maximum height of 55mm must not be exceeded in the 30mm front border area of the carrier.

		Minilab
Technical Data - Footprint		
Weight (kg)		
	Machine	70
	Optional Cooling Device	26
Machine Dimensions (mm)		
l	Length	715
t	Depth	625
h	Height	580
Power Connection		
	Length	3m connection cable with plug
Water Connection (mm)		
z1	Length	0
z	Depth	150
Optional Cooling Device (mm)		
l _c	Length	580
t _c	Depth	290
h _c	Height	470

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